

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L3	3	("5600180" "5757078" "5926694").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2007/12/22 17:03
L4	13	("4003772" "4491500" "4770740" "5043294" "5081796" "5278105" "5423716" "5529953" "5549212" "5602423" "5899706" "5923563" "5948573").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2007/12/22 17:17
L5	33	(@ad<"20000216") and ("438"/108.ccls. or "257"/778.ccls.) and ((wafer near scale) or "wsp" or "wisp")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/12/22 17:47
L6	40	(@ad<"20000216") and ((wafer and (cmp or polish\$3 or planarization or planar)) near (polymer or resin or polyimide adhere or adhesive or encapsulant or compliant or epoxy or encapsulation or underfill or silicone or stress or porous))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/12/22 18:03
L7	3	(@ad<"20000216") and (257/787.ccls.) and ((wafer near scale) or "wsp" or "wisp")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/12/22 17:48
L8	252	(@ad<"20000216") and "438"/\$.ccls. and ((wafer near scale) or "wsp" or "wisp")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/12/22 18:02
L9	181	L8 and (polymer or resin or polyimide adhere or adhesive or encapsulant or compliant or epoxy or encapsulation or underfill or silicone or stress or porous)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/12/22 17:49
L10	10	("3893156" "4398993" "4417948" "4612083" "4764484" "4824802" "4861425" "4936950" "5032541" "5057453").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2007/12/22 17:56

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L11	53	(@ad<"20000216") and (257/778.ccls. or 438/108.ccls.) and (cmp or polish\$3 or planarization or planar) and (wafer with(polymer or resin or polyimide adhere or adhesive or encapsulant or compliant or epoxy or encapsulation or underfill or silicone or stress or porous))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/12/22 18:04
L12	53	(@ad<"20000216") and (257/778.ccls. or 438/108.ccls.) and (cmp or polish\$3 or planarization or planar) and (wafer with (polymer or resin or polyimide adhere or adhesive or encapsulant or compliant or epoxy or encapsulation or underfill or silicone or stress or porous))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/12/22 18:09
L13	18	("4676868" "5030799" "5218234" "5355580" "5442240" "5488200" "5543585" "5600180" "5621225" "5641946" "5650667" "5659203" "5703406" "5704116" "5710071" "5751553" "5956605" "6022761"). PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2007/12/22 18:07
L14	2283	(@ad<"20000216") and ("257"/\$.ccls. or "438"/\$.ccls. or (wafer adj scale) or wisp or wsp or csp) and (cmp or polish\$3 or planarization or planar) and (wafer with (polymer or resin or polyimide adhere or adhesive or encapsulant or compliant or epoxy or encapsulation or underfill or silicone or stress or porous))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/12/22 18:20
L15	2225	L14 not L8	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/12/22 18:21
L16	1897	L15 and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/12/22 18:21

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L17	328	L15 not L16	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/12/22 18:21
S1	1	("6710454").PN.	USPAT; USOCR	OR	OFF	2007/12/22 13:00
S2	67	(@ad<"20000216") and (438/598,959.ccls. or 257/778.ccls.) and (wafer with (encapsulant or compliant or epoxy or encapsulation or underfill or silicone or stress))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/12/22 13:12
S3	14	(@ad<"20000216") and (257/e21.526.ccls.) and (wafer with (encapsulant or compliant or epoxy or encapsulation or underfill or silicone or stress))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/12/22 13:08
S4	51	(@ad<"20000216") and (257/e21.122.ccls.) and (wafer with (encapsulant or compliant or epoxy or encapsulation or underfill or silicone or stress))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/12/22 13:13
S5	51	S4 not S2	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/12/22 13:08
S6	51	S4 not S3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/12/22 13:09
S7	666	(@ad<"20000216") and ("438"/\$.ccls. or "257"/\$.ccls.) and ((wafer near scale) or "wsp" or "wls")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/12/22 13:13

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S8	666	(@ad<"20000216") and ("438"/\$.ccls. or "257"/\$.ccls.) and ((wafer near scale) or "wsp" or "wlspr")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/12/22 17:24
S9	106	S8 and ((hole or open\$3 or recess or via or trench or etch\$3 or laser) with (encapsulant or compliant or epoxy or encapsulation or underfill or silicone or stress))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/12/22 15:31
S10	62	S8 and (wafer with (polymer or resin or polyimide adhere or adhesive or encapsulant or compliant or epoxy or encapsulation or underfill or silicone or stress)) and (cmp or polish\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/12/22 15:38
S11	1185	(@ad<"20000216") and ((wafer and (cmp or polish\$3)) with (polymer or resin or polyimide adhere or adhesive or encapsulant or compliant or epoxy or encapsulation or underfill or silicone or stress)) and (cmp or polish\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/12/22 15:38
S12	1185	(@ad<"20000216") and ((wafer and (cmp or polish\$3)) with (polymer or resin or polyimide adhere or adhesive or encapsulant or compliant or epoxy or encapsulation or underfill or silicone or stress))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/12/22 15:44
S13	28	(@ad<"20000216") and ((wafer and (cmp or polish\$3)) near (polymer or resin or polyimide adhere or adhesive or encapsulant or compliant or epoxy or encapsulation or underfill or silicone or stress))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/12/22 17:45
S14	7	("4904610" "5393706" "5445559" "5516728" "5527744" "5605489" "5888883").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2007/12/22 15:39
S15	29	("4904610").URPN.	USPAT	OR	OFF	2007/12/22 15:41

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S16	702	S12 and ((fill\$3 or plat\$3 or coat\$3 or deposit\$3) with (trench or via\$3 or open\$3 or hole\$1 or polymer or resin or polyimide adhere or adhesive or encapsulant or compliant or epoxy or encapsulation or underfill or silicone or stress))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/12/22 15:46
S17	702	S12 and ((fill\$3 or plat\$3 or coat\$3 or deposit\$3) with (trench or via\$3 or open\$3 or hole\$1 or polymer or resin or polyimide adhere or adhesive or encapsulant or compliant or epoxy or encapsulation or underfill or silicone or stress))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/12/22 15:47
S18	302	S12 and ((fill\$3 or plat\$3 or coat\$3 or deposit\$3) with (trench or via\$3 or open\$3 or hole\$1))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/12/22 15:47